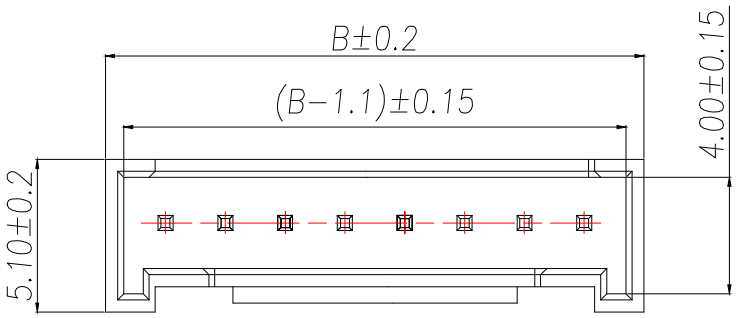
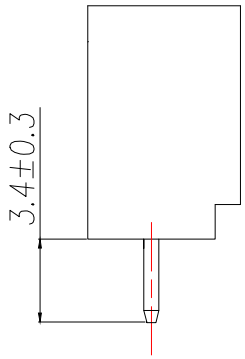



技术要求:

1.塑件材料:PA66(UL-94V-0)

2.接触件:黄铜镀锡

3.接触电阻:≤10mΩ

4.绝缘电阻:≥100MΩ

5.额定电压:250V AC DC

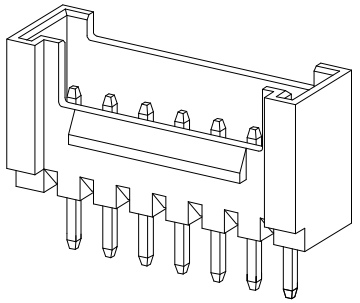
6.额定电流:2.0A AC DC

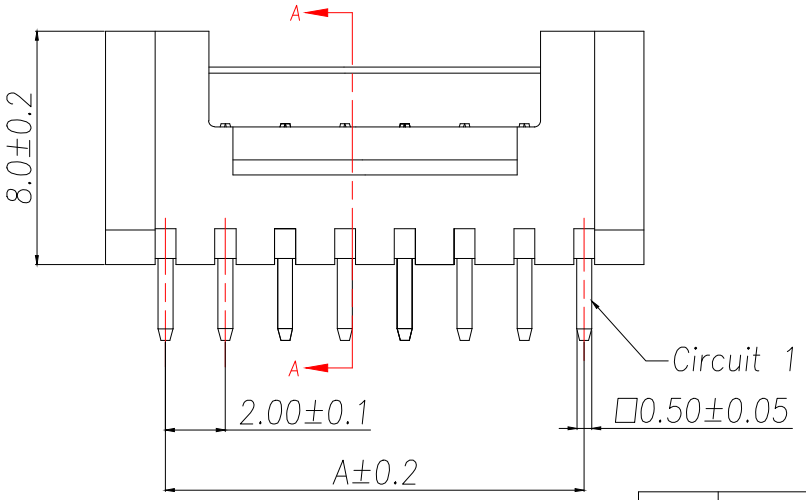
7.耐压:能承受1000V AC/Minute

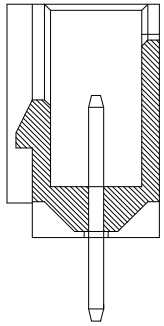
8.工作温度:-25°~+85°

9.可焊性试验:浸锡面积≥95%温度235$^{+5}_{0}$°,时间2.5±0.5秒

10.铅和镉等六大有害物质含量要符合环保要求.

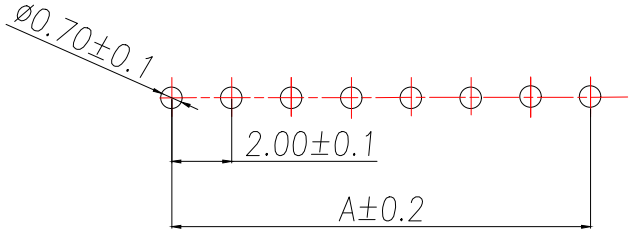




SECTION A-A

| Part No | Pin | A | B |
|---|---|---|---|
| HY2.0-2 | 2 | 2.00 | 6.00 |
| HY2.0-3 | 3 | 4.00 | 8.00 |
| HY2.0-4 | 4 | 6.00 | 10.00 |
| HY2.0-5 | 5 | 8.00 | 12.00 |
| HY2.0-6 | 6 | 10.00 | 14.00 |
| HY2.0-7 | 7 | 12.00 | 16.00 |
| HY2.0-8 | 8 | 14.00 | 18.00 |
| HY2.0-9 | 9 | 16.00 | 20.00 |
| HY2.0-10 | 10 | 18.00 | 22.00 |
| HY2.0-11 | 11 | 20.00 | 24.00 |
| HY2.0-12 | 12 | 22.00 | 26.00 |
| HY2.0-13 | 13 | 24.00 | 28.00 |
| HY2.0-14 | 14 | 26.00 | 30.00 |
| HY2.0-15 | 15 | 28.00 | 32.00 |




SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

| 序号 | 名称 | 材料 | 数量 | 备注 |
|---|---|---|---|---|
| 2 | 端子Contact | 黄铜 | N*1 | 电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN |
| 1 | 基座Wafer | PA66(UL94V-0) | 1 | 白色 |

| 制图 DRAWN | 变更内容 DESCRIPTION | 日期 DATE |
|---|---|---|
| | | |
| | | |
| | | |

| GENERL TOLERANCE | |
|---|---|
| .X±0.20 | ±2° |
| .XX±0.10 | |
| .XXX±0.05 | |

| | | | |
|---|---|---|---|
| 制图 DRAWING | ROSE | | |
| 审核 CHECK | LEO | | |
| 核准 APPROVAL | JOHN | | |
| 单位 UNITS | MM | 比例 SCALE | 1:1 |

| | | | |
|---|---|---|---|
| 料号 PART NO. | BTC-HY2.0-N*A | 版本 REV. | A |
| 品名 TITLE | WAFER HY2.0MM 直针 | 页次 SHEET | 1/1 |
| 客户料号 CUTM.NO. | | | |

深圳市宝通成电子有限公司